

185HR Laminate and Prepreg

185HR is a proprietary, high performance resin system with a Tg >170°C for multilayer Printed Wiring Board (PWB) applications where maximum thermal performance and reliability are required. 185HR laminate and prepreg products are manufactured using Isola's patented technology, reinforced with electrical grade (E-glass) glass fabric. This system delivers a 340°C decomposition temperature, a lower Z-axis expansion and offers lower loss compared to competitive products in this space.

The 185HR system is also laser fluorescing and UV blocking for maximum compatibility with Automated Optical Inspection (AOI) systems, optical positioning systems and photoimageable solder mask imaging.

www.isola-group.com/products/185HR

ORDERING INFORMATION:

Contact your local sales representative or visit **www.isola-group.com** for further information.

Isola Group 3100 West Ray Road Suite 301 Chandler, AZ 85226 Phone: 480-893-6527 Fax: 480-893-1409 info@isola-group.com Isola Asia Pacific (Hong Kong) Ltd. Unit 3512 - 3522, 35/F No. 1 Hung To Road, Kwun Tong, Kowloon, Hong Kong Phone: 852-2418-1318 Fax: 852-2418-1533 info.hkg@isola-group.com Isola GmbH Isola Strasse 2 D-52348 Düren, Germany Phone: 49-2421-8080 Fax: 49-2421-808164 info-dur@isola-group.com

185HR

Data Sheet

Tg 170, Td 340 Dk 4.01, Df 0.020 /21 /24 /26 /98 /99 /101 /126

Features

- High Thermal Performance
 - ► Tg: 170°C (DSC) (Base Laminate)
 - ► Td: 340°C (TGA @ 5% wt loss)
 - ► Low CTE for reliability
- T260: 60 minutes
- T288: >15 minutes
- Lead-free Compatible and RoHS Compliant
- UV Blocking and AOI Fluorescence
 - High throughput and accuracy during PCB fabrication and assembly
- Superior Processing
 - ► Closest to conventional FR-4 processing
- Core Material Standard Availability
 - ► Thickness: 0.002" (0.05 mm) to 0.060"/0.062" (1.5 mm)
 - ▶ Available in full size sheet or panel form
- Prepreg Standard Availability
 - ▶ Roll or panel form
 - ▶ Tooling of prepreg panels available
- Copper Foil Type Availability
 - ► Standard HTE Grade 3
 - ► RTF (Reverse Treat Foil)
- Copper Weights
 - ½, 1 and 2 oz (18, 35 and 70 μm) available
 - ▶ Heavier copper available upon request
 - ► Thinner copper foil available upon request
- Glass Fabric Availability
 - Standard E-glass
 - ▶ Square weave glass fabric available
- Industry Approvals
 - ▶ IPC-4101C /21 /24 /26 /98 /99 /101 /126
 - ▶ UL File Number E41625
 - ▶ Qualified to UL's MCIL Program

185HR Specifications

| | | Typical Values | | | |
|--|--|---|---|----------------------|---|
| | Property | | | Units Test Method | |
| Troperty | | Typical Value | Specification | Metric (English) | IPC-TM-650 (or as noted) |
| Glass Transition Temperature (Tg) by DSC | | 170 | 170-200 | °C | 2.4.25 |
| Decomposition Temperature (Td) by TGA @ 5% weight loss | | 340 | - | °C | ASTM D3850 |
| T260 | | 60 | - | Minutes | ASTM D3850 |
| T288 | | >15 | _ | Minutes | ASTM D3850 |
| CTE, Z-axis | A. Pre-Tg B. Post-Tg | 40 220 | AABUS - | ppm/°C | 2.4.24 |
| CTE, X-, Y-axes | A. Pre-Tg B. Post-Tg | 13/14 14/17 | AABUS - | ppm/°C | 2.4.24 |
| Z-axis Expansion (50-260°C) | | 2.7 | _ | % | 2.4.24 |
| Thermal Conductivity | | 0.4 | - | W/mK | ASTM D5930 |
| Thermal Stress 10 sec @ 288°C (550.4°F) | A. Unetched B. Etched | Pass | Pass Visual | Rating | 2.4.13.1 |
| Dk, Permittivity (Laminate & prepreg as laminated) Tested at 50% resin | A. @ 100 MHz (HP4285A) B. @ 1 GHz (HP4291A) C. @ 2 GHz (Bereskin Stripline) D. @ 5 GHz (Bereskin Stripline) E. @ 10 GHz (Bereskin Stripline) | 4.13 4.04 4.01 3.88 3.88 | 5.4 - - - - | - | 2.5.5.3 2.5.5.9 2.5.5.5 2.5.5.5 2.5.5.5 |
| Df, Loss Tangent (Laminate & prepreg as laminated) Tested at 50% resin | A. @ 100 MHz (HP4285A) B. @ 1 GHz (HP4291A) C. @ 2 GHz (Bereskin Stripline) D. @ 5 GHz (Bereskin Stripline) E. @ 10 GHz (Bereskin Stripline) | 0.0158 0.0192 0.0200 0.0235 0.0236 | 0.035 - - - - | - | 2.5.5.3 2.5.5.9 2.5.5.5 2.5.5.5 2.5.5.5 |
| Volume Resistivity | A. 96/35/90 B. After moisture resistance C. At elevated temperature | - 3.0x10 ⁸ 7.0x10 ⁸ | 1.0x10 ⁶ - 1.0x10 ³ | MΩ-cm | 2.5.17.1 |
| Surface Resistivity | A. 96/35/90 B. After moisture resistance C. At elevated temperature | - 3.0x10 ⁶ 2.0x10 ⁸ | 1.0x10 ⁴ - 1.0x10 ³ | ΜΩ | 2.5.17.1 |
| Dielectric Breakdown | | >50 | _ | kV | 2.5.6 |
| Arc Resistance | | 115 | 60 | Seconds | 2.5.1 |
| Electric Strength (Laminate & prepreg as laminated) | | 54 (1350) | 30 (750) | kV/mm (V/mil) | 2.5.6.2 |
| Comparative Tracking Index (CTI) | | 3 (175-249) | - | Class (Volts) | UL-746A ASTM D3638 |
| Peel Strength | A. Low profile copper foil and very low profile – all copper weights >17 microns B. Standard profile copper 1. After thermal stress 2. At 125°C (257°F) 3. After process solutions | 1.14 (6.5) - 1.25 (7.0) 1.25 (7.0) 1.14 (6.5) | 0.70 (4.0) - 0.80 (4.5) 0.70 (4.0) 0.55 (3.5) | N/mm (lb/inch) | 2.4.8.2 2.4.8.3 - - |
| Flexural Strength | A. Lengthwise direction B. Crosswise direction | 97,100 54,100 | - | lb/inch ² | 2.4.4 |
| Tensile Strength | A. Lengthwise direction B. Crosswise direction | 53,337 35,678 | - | lb/inch² | - |
| Young's Modulus | A. Grain direction B. Fill direction | 3770 3337 | - | ksi | WW |
| Poisson's Ratio | A. Grain direction B. Fill direction | 0.172 0.155 | - | - | XX |
| Moisture Absorption | | 0.15 | _ | % | 2.6.2.1 |
| Flammability (Laminate & prepreg as laminated) | | V-0 | - | Rating | UL 94 |
| Max Operating Temperature | | 130 | UL Cert | °C | _ |

The data, while believed to be accurate and based on analytical methods considered to be reliable, is for information purposes only. Any sales of these products will be governed by the terms and conditions of the agreement under which they are sold.

www.isola-group.com/products/185HR



